

Title (en)  
COMPONENT AND METHOD FOR THE PRODUCTION THEREOF

Title (de)  
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Title (fr)  
COMPOSANT ET SON PROCEDE DE REALISATION

Publication  
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Application  
**EP 00934843 A 20000622**

Priority  
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Abstract (en)  
[origin: WO0101478A1] A substrate (1) is provided with a mainly copper layer (2). A wire (3) is joined to the copper layer (2) by means of bonding and by formation of an intermetallic compound, whereby a hard layer (5) which is applied to the mainly copper layer (2) is broken up in the bond area. The hard layer is stable at a temperature of at least 80 DEG C. At this temperature said layer acts as an oxygen diffusion barrier, acting upon aluminium in a manner similar to an aluminium oxide layer which is formed in a normal environment.

IPC 1-7  
**H01L 21/60**; **H01L 23/485**

IPC 8 full level  
**H01L 21/3205** (2006.01); **H01L 21/60** (2006.01); **H01L 23/485** (2006.01); **H01L 23/52** (2006.01)

CPC (source: EP KR US)  
**H01L 23/485** (2013.01 - KR); **H01L 24/03** (2013.01 - EP US); **H01L 24/05** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 24/85** (2013.01 - EP US); **H01L 24/45** (2013.01 - EP US); **H01L 2224/04042** (2013.01 - EP US); **H01L 2224/05556** (2013.01 - EP US); **H01L 2224/05647** (2013.01 - EP US); **H01L 2224/45** (2013.01 - EP); **H01L 2224/45015** (2013.01 - EP US); **H01L 2224/45124** (2013.01 - EP US); **H01L 2224/45144** (2013.01 - EP US); **H01L 2224/45147** (2013.01 - EP US); **H01L 2224/48** (2013.01 - EP); **H01L 2224/48091** (2013.01 - EP); **H01L 2224/4847** (2013.01 - EP US); **H01L 2224/48647** (2013.01 - EP US); **H01L 2224/48747** (2013.01 - EP US); **H01L 2224/48847** (2013.01 - EP US); **H01L 2224/85** (2013.01 - EP); **H01L 2224/85205** (2013.01 - EP US); **H01L 2224/85375** (2013.01 - EP US); **H01L 2224/85948** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01007** (2013.01 - EP US); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/01014** (2013.01 - EP US); **H01L 2924/01015** (2013.01 - EP US); **H01L 2924/01018** (2013.01 - EP US); **H01L 2924/01019** (2013.01 - EP US); **H01L 2924/01022** (2013.01 - EP US); **H01L 2924/01023** (2013.01 - EP US); **H01L 2924/01024** (2013.01 - EP US); **H01L 2924/01025** (2013.01 - US); **H01L 2924/01028** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP); **H01L 2924/01039** (2013.01 - EP US); **H01L 2924/01041** (2013.01 - EP US); **H01L 2924/0105** (2013.01 - EP US); **H01L 2924/01057** (2013.01 - EP US); **H01L 2924/01068** (2013.01 - EP US); **H01L 2924/01073** (2013.01 - EP US); **H01L 2924/01078** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/01327** (2013.01 - EP US); **H01L 2924/014** (2013.01 - EP US); **H01L 2924/04953** (2013.01 - EP US); **H01L 2924/05042** (2013.01 - EP US); **H01L 2924/14** (2013.01 - EP US); **H01L 2924/19043** (2013.01 - EP US); **H01L 2924/20752** (2013.01 - EP US)

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